



Amphenol

Industrial Global Operations

Power to Board

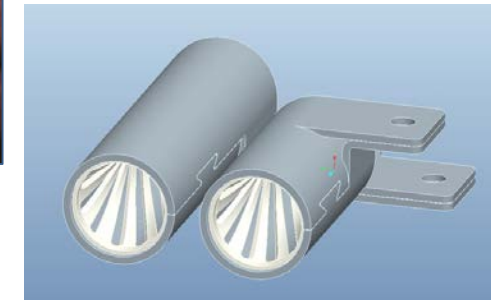
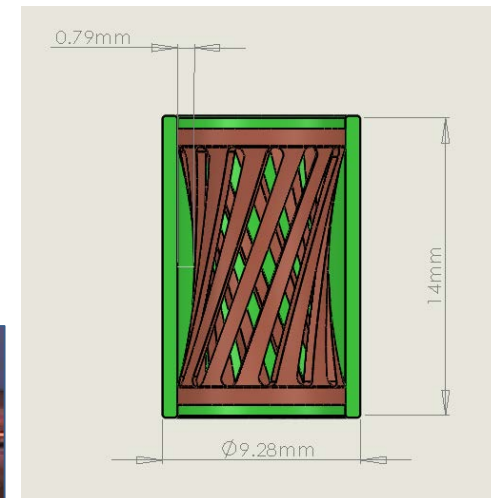
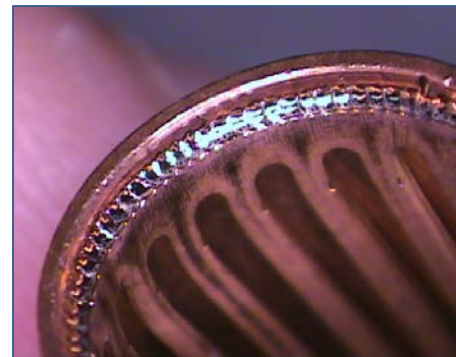
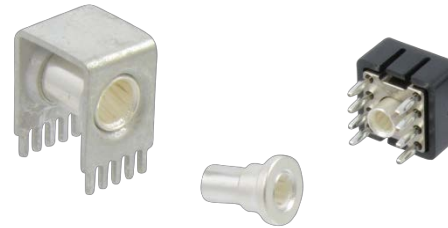
Technology Trends in the Power Board Market

- Higher integration is driving the demand for higher currents, 70A to 300A
- Big Data and Data Centers are driving the need for more efficient power connections
- Higher speeds are driving the need for improved electrical performance and signal integrity
- Facebook's "Open Compute" consortium push for Data Center standardization



Technology Trends

- Higher power density (more current/less space)
- 70+ Amp current demand
- Low resistance connections
- Low inductance power distribution
- Quick turn custom packaging
- Integrated DC power distribution systems, Board to Board, Busbar to Board. Cable to Board
- Robust mechanical design / blindmate



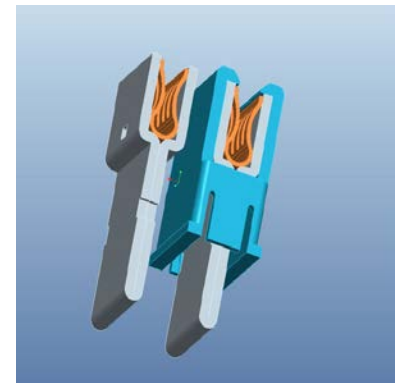
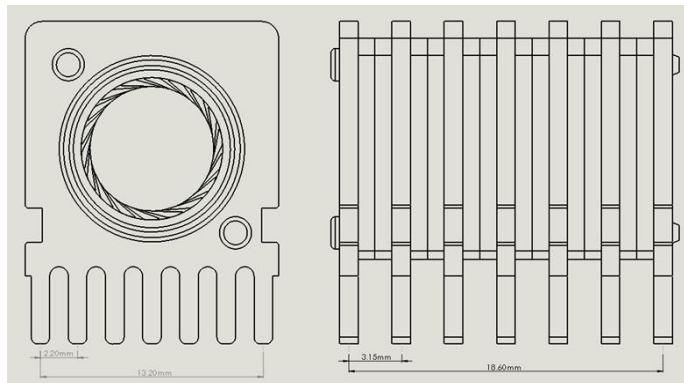
Amphenol Power to the Board

Today:

- Broad portfolio of board level power products based on the proven RADSOK power contact
- Existing base of OEM customers including IBM, Cisco, HP, Dell, Brocade, Oracle, Juniper, Motorola, GE

One Year

- Expanding our power portfolio to address need for improved power efficiency and electrical performance
- RadEdge busbar connector to be released in Q4 to address Facebook's Open Compute data center power standard



The RADSOK® Solution

Amphenol Industrial Operations has developed a portfolio of compact, high amperage connectors for single-point connections to printed circuit boards (PCB's).

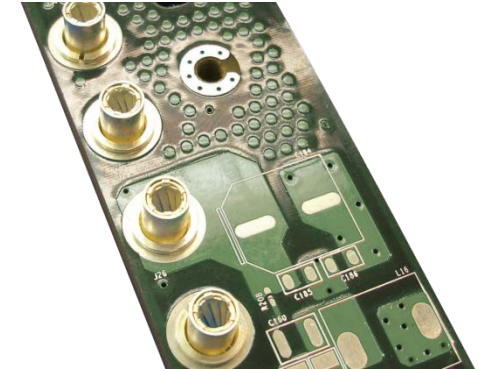


RADSERT™,
PowerBlok™
PGY™



Each of these products incorporates our proprietary
RADSOK® technology

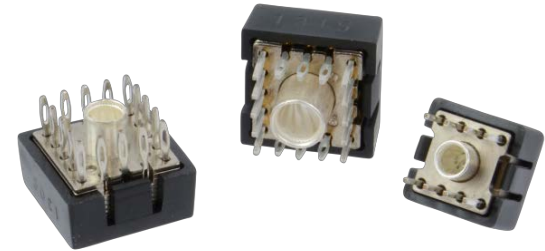
RADSERT™



- **RADSERTs™** are a versatile, low profile, single point, high current contact that can be applied to a PCB or busbar
- RADSERTs™ with enhanced lead in and mis-alignment tolerance are available to handle blindmate applications.
- “Press-fit” or solder version termination
- Current carrying capability up to 120A.

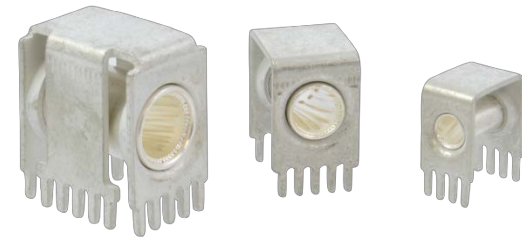
Custom sizes are easily configured for specific applications.

POWERBLOK™



- PowerBlok™ features a robust mechanical design and RADSOK radial contact design that ensures multiple redundant points of electrical contact
- Generous mis-alignment tolerance or “float” for blindmate connections
- Press fit compliant pin termination for high speed backplane and midplane applications
- 2 piece pin and socket mezzanine stacking configuration available
- Available with current rating up to 200A
- RADSOK® contact and small footprint are an advantage for engineers who are limited in their PCB design with size and weight requirements.

PGY'S™



- The **PGY**™ is an orthogonal card edge connector available in multiple sizes carrying up to 200 AMPS
- The PGY™ is terminated to the PCB through a solder reflow process, press fit termination is in development
- The design of the PGY™ is optimized to dissipate heat and to delivery high power evenly to the board.
- Robust mechanical design suitable for blindmate drawer applications